



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01457	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01457		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/10/2017	10:13:58 AM	TEXAS INSTRUMENTS

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